



Material Content Data Sheet



Sales Product Name		IPG20N06S2L-65A		Issued		31. July 2018		
MA#		MA002182488						
Package		PG-TDSON-8-10		Weight*		98.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.939	0.95	0.95	9530	9530
chip_2	inorganic material	silicon	7440-21-3	0.939	0.95	0.95	9530	9530
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	iron	7439-89-6	0.046	0.05		471	
wire	non noble metal	copper	7440-50-8	46.380	47.06	47.12	470473	471085
	non noble metal	aluminium	7429-90-5	0.783	0.79	0.79	7946	7946
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		915	
	plastics	epoxy resin	-	6.408	6.50		65000	
leadfinish	inorganic material	silicondioxide	60676-86-0	38.628	39.18	45.77	391832	457747
	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14165	14165
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6118	6133
solder	non noble metal	tin	7440-31-5	0.047	0.05		477	
	noble metal	silver	7440-22-4	0.059	0.06		597	
*deviation	non noble metal	lead	7439-92-1	2.247	2.28	2.39	22790	23864
	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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